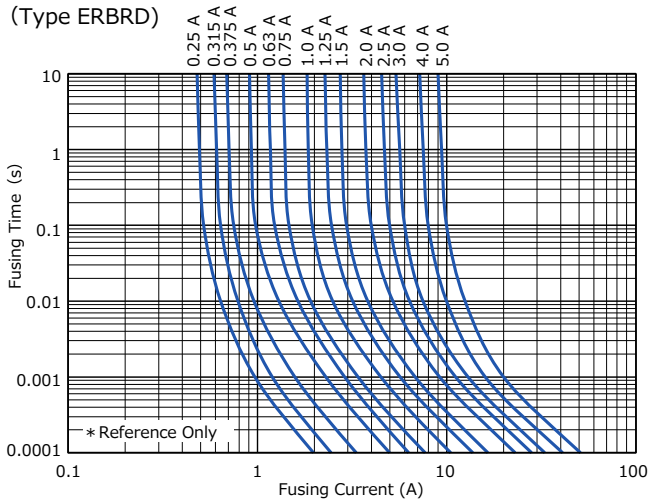
Fusing Characteristics (25 °C typical)

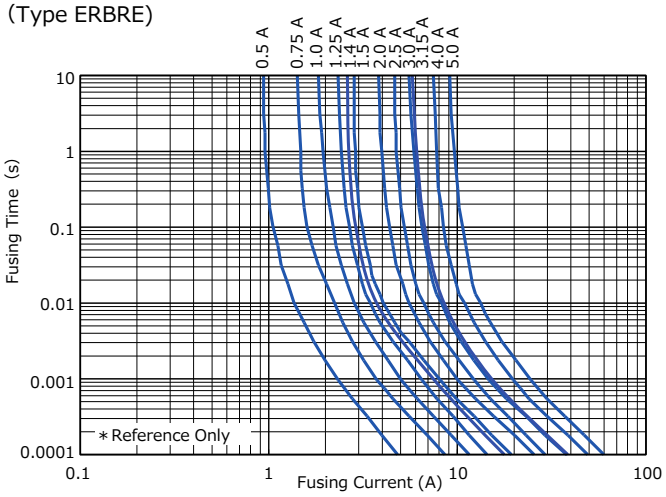
●0402 inch / 1005 mm size

(Type ERBRD)



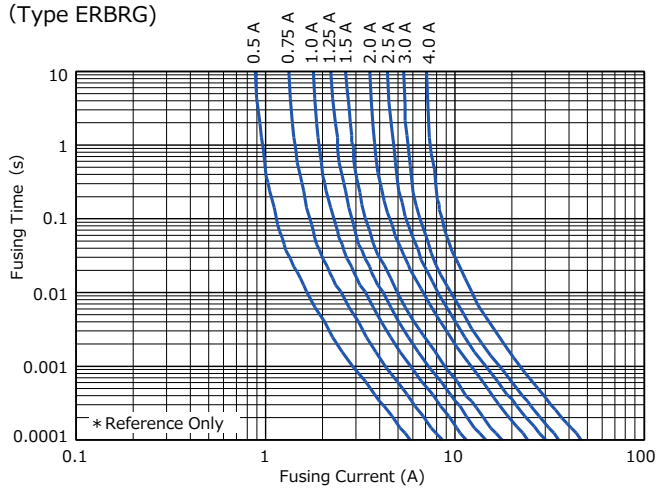
●0603 inch / 1608 mm size

(Type ERBRE)



●1206 inch / 3216mm size

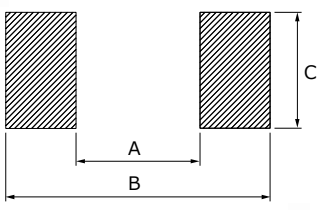
(Type ERBRG)



Perfomance

Test Item	Performance Requirements	Test Conditions
Resistance	Within Specified Tolerance	25 ℃
Resistance to Soldering Heat	±10 %	260 ℃±5 ℃, 10 s
Rapid Change of Temperature	±10 %	-40 ℃ (30 min.) / + 125 ℃ (30 min.), 5 cycles
Damp Heat, Steady State	±10 %	60 ℃, 90 % to 95 %RH, 1000 h (no load)
Load Life in Humidity	±10 %	60 ℃, 90 % to 95 %RH, Load: 70 % rated current, 1000 h
Endurance at 70 °C	±10 %	70 ℃, Load: 70 % rated current, 1000 h

Recommended Soldering Conditions



Part No. (inch size)	Dimensions(mm)		
	A	B	C
ERBRD (0402)	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6
ERBRE (0603)	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0
ERBRG (1206)	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8

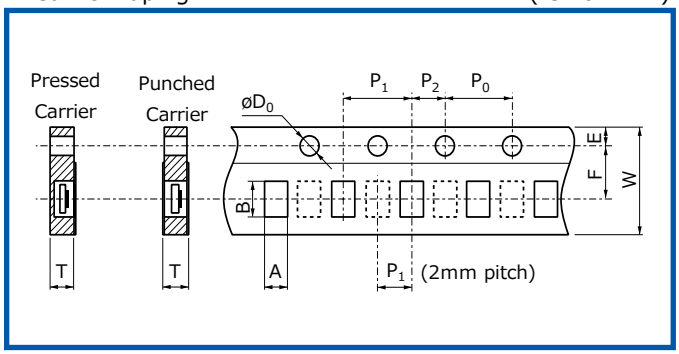
Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use.

Packaging Methods (Taping)

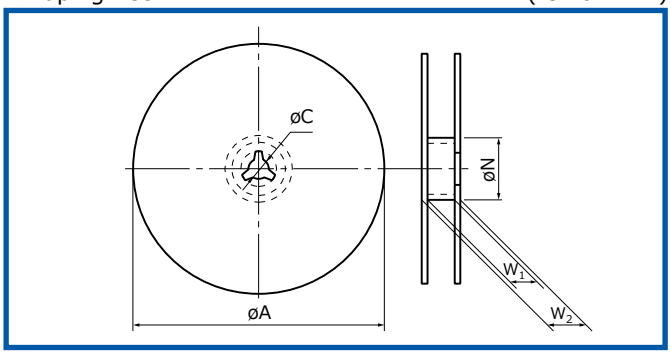
●Standard Quantity

Part No.	Size (inch)	Kind of Taping	Pitch (P_1)	Quantity
ERBRD	0402	Pressed Carrier Taping	2 mm	10,000 pcs / reel
ERBRE	0603	Punched Carrier Taping	4 mm	5,000 pcs / reel
ERBRG	1206			

●Carrier Taping (Unit : mm)



●Taping Reel (Unit : mm)



Part No.	A	B	W	F	E
ERBRD	0.68 ±0.10	1.20 ±0.10	8.00 ±0.20	3.50 ±0.05	1.75 ±0.10
ERBRE	1.10 ±0.10	1.90 ±0.10			
ERBRG	2.00 ±015	3.60 ±020			

Part No.	P_1	P_2	P_0	$øD_0$	T
ERBRD	2.00 ±0.10	2.00 ±0.05	4.00 ±0.10	1.50 +0.10 0	0.67 ±0.07
ERBRE	4.00 ±0.10				0.78 ±0.07
ERBRG					0.84 ±0.07

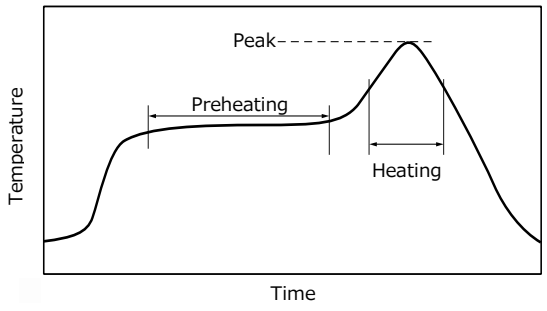
Part No.	øA	øN	øC	W_1	W_2
ERBRD ERBRE ERBRG	180.0 0 -1.5	60 +1.0 0	13.0 ±0.2	9.0 +1.0 0	11.4 ±1.0

Recommended Soldering Conditions

Recommendations and precautions are described below

● **Recommended soldering conditions for reflow**

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s
Main heating	Above 200 ℃	30 s to 40 s
Peak	235 ± 5 ℃	max. 10 s

For lead-free soldering (Example :Sn/Ag/Cu)

	Temperature	Time
Preheating	150 ℃ to 180 ℃	60 s to 120 s
Main heating	Above 230 ℃	30 s to 40 s
Peak	max. 260 ℃	max. 10 s

● **Recommended soldering conditions for flow**

	For soldering		For lead-free soldering	
	Temperature	Time	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s	150 ℃ to 180 ℃	60 s to 120 s
Soldering	245±5 ℃	20 s to 30 s	max. 260 ℃	max. 10 s

《Repair with hand soldering》

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.

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